

Title (en)  
METHOD FOR ELECTROPLATING METALLIC AND NON-METALLIC ENDLESS PRODUCTS AND DEVICE FOR CARRYING OUT SAID METHOD

Title (de)  
VERFAHREN ZUM ELEKTROLYTISCHEN BESCHICHTEN VON METALLISCHEN ODER NICHTMETALLISCHEN ENDLOSPRODUKTEN UND VORRICHTUNG ZUR DURCHFÜHRUNG DES VERFAHRENS

Title (fr)  
PROCEDE DE REVETEMENT ELECTROLYTIQUE DE PRODUITS CONTINUS METALLIQUES OU NON METALLIQUES ET DISPOSITIF POUR LA MISE EN OEUVRE DE CE PROCEDE

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Application  
**EP 98922715 A 19980415**

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Abstract (en)  
[origin: US6340422B1] The present invention is directed to processes and devices for performing the processes comprising electroplating one or more metallic or non-metallic continuous products with metals or metal alloys in a continuous process from aprotic electrolytes free of water and oxygen, wherein the continuous product is passed through a lock system (1) into an encapsulated coating plant under inert gas atmosphere, and the following steps are performed at temperatures  $\leq 120^{\circ}\text{C}$ : activating the continuous product to be coated; rinsing the continuous product to be coated; contacting the continuous product to be coated; electroplating the continuous product to be coated using a metal or metal alloy; drying the coated continuous product; discharge of the coated continuous product from the plant through a lock system.

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**C25D 7/06**; **C25D 3/44**

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